6-1761614-2 <

STEP-Z

TE Internal #: 6-1761614-2 PCB Mount Header, Vertical, Board-to-Board, 200 Position, 1.3 mm [.051 in] Centerline, Partially Shrouded, Gold, Surface Mount -Solder Ball

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 200

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Partially Shrouded



Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	200
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Dielectric Withstanding Voltage (Max)	500 VAC
Insulation Resistance	18 MΩ
Operating Voltage	48 VAC
Body Features	
Primary Product Color	Natural
Contact Features	

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Contact Layout	Matrix
Mating Tab Width	1 mm[.04 in]
Mating Tab Thickness	.2 mm[.008 in]
Contact Shape & Form	Dual Beam, Single Beam, Square
PCB Contact Termination Area Plating Material	Tin-Silver
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.76 μm[29.9212 μin]
Contact Type	Tab
Contact Current Rating (Max)	1 A
Termination Features	
Termination Method to PCB	Surface Mount - Solder Ball
Mechanical Attachment	
Mating Retention	With
Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	1.3 mm[.051 in]
Housing Material	Thermoplastic
Dimensions	
Connector Height	12.95 mm[.509 in]
Row-to-Row Spacing	2 mm[.079 in]
Stack Height	17 mm, 23 mm, 27 mm[1.063 in]
PCB Thickness (Recommended)	1.57 mm[.8 in]
Usage Conditions	
Operating Temperature Range	0 – 100 °C[32 – 212 °F]
Operation/Application	
Assembly Process Feature	None
	Dower & Signal
Circuit Application	Power & Signal

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UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	25
Packaging Method	Tray
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

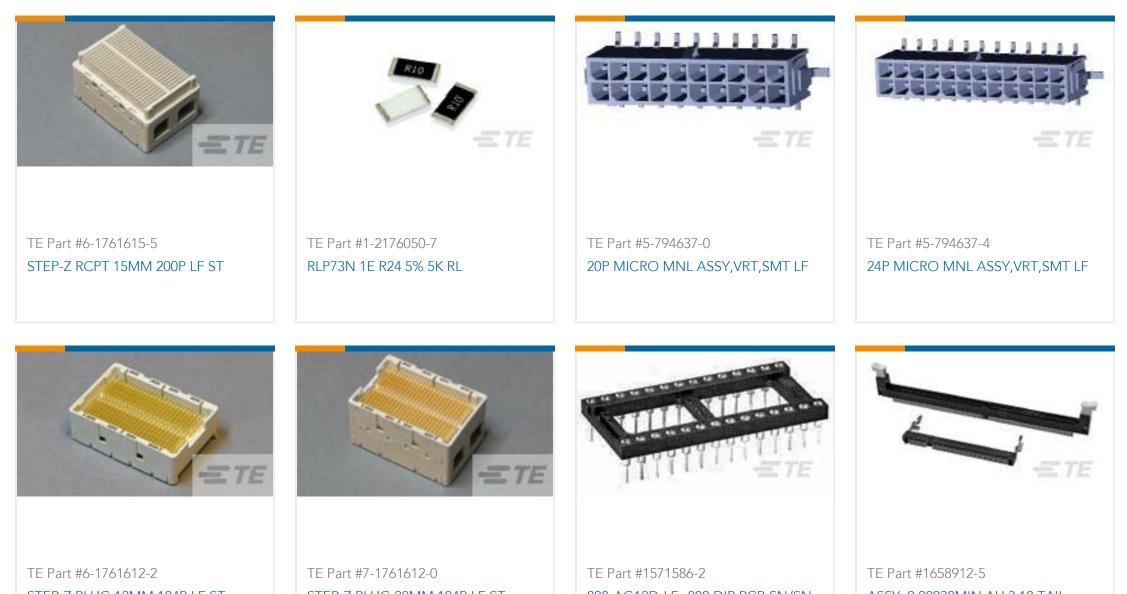


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Customers Also Bought



Documents

Product Drawings STEP-Z PLUG 12MM 200P LF ST

English

CAD Files

Customer View Model

ENG_CVM_CVM_6-1761614-2_B.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_6-1761614-2_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_6-1761614-2_B.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

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Datasheets & Catalog Pages STEP-Z Interconnection System

English

Product Specifications Application Specification

English